

Bill of Materials

TI DESIGNS

Part #: CC256x QFN EM Rev 1.2B

Literature # TIDR111

Reference Design: CC256XEM-RD

DESIGNATOR	QUANTITY	DESCRIPTION	MANUFACTURER	PART NUMBER	ALTERNATIVE MANUFACTURER	ALTERNATIVE PART NUMBER	NOTE
ANT1	1	PCB ANTENNA	N/A	N/A			
C1, C5, C10, C34	4	CAP CER 10UF 6.3V X5R 0603	Taiyo Yuden	JMK107BJ106MA-T			
C2, C6, C9, C11, C12, C13, C14, C15, C16, C17, C27, C28, C29, C30, C33, C35	16	CAP CER 0.1UF 6.3V 10% X7R 0402	Kemet	C0402C104K9RACTU			
C18, C19, C24, C36	4	CAP CER 0.1UF 6.3V 10% X7R 0402	Kemet	C0402C104K9RACTU			DO NOT INSTALL
C7, C20, C21	3	CAP CER 1.0UF 6.3V X5R 10% 0402	Taiyo Yuden	JMK105BJ105KV-F			
C32	1	CAP CER 1.0UF 6.3V X5R 10% 0402	Taiyo Yuden	JMK105BJ105KV-F			DO NOT INSTALL
C8	1	CAP CER 0.01uF 6.3V 10% X5R 0402	Murata	GRM155R60J103KA01D			
C22, C23	2	CAP CER 10PF 50V 5% NP0 0402	Murata Electronics	GRM1555C1H120JZ01D			
C25, C26	2	CAP CER .47UF 6.3V X5R ±10% 0402	Taiyo Yuden	JMK105BJ474KV-F			
C31	1	CAP CER 22PF 25V 5% NP0 0201	Murata Electronics North America	GRM0335C1E220JD01D			
D1	1	LED GREEN HI BRT SS TYPE LO CUR SM	OSRAM Opto Semiconductors Inc	LG L29K-G2J1-24-Z			
FB1, FB2, FB3	3	FERRITE BEAD 68 OHM 0402	Taiyo Yuden	BK1005HS680-T			
FL1	1	FILTER CER BAND PASS 2.45GHZ SMD	Murata Electronics	LFB212G45SG8C341			
LB1	1	650x200 Label UL,CSA,AGA approved	Brady	THT-14-423-10			
OSC1	1	Misc. MC_32.768kHz_OSC_4_SM_130x60x40	Micro Crystal	OV-7604-C7			DO NOT INSTALL
P1	1	PCB PRINTED	N/A	N/A			DO NOT INSTALL
P2	1	HEADER 2x9 100 THVT M 430L	Samtec	HMTSW-109-07-G-D-230			DO NOT INSTALL
P3	1	RECEPTACLE_CON_COAXIAL_UFL-R-SMT	Hirose	U.FL-R-SMT-1			
R6, R18, R26, R30, R35	5	RES 0.0 OHM 1/10W 0402 SMD	Panasonic - ECG	ERJ-2GE0R00X			DO NOT INSTALL
R1, R2, R3, R5, R8, R9, R11, R29, R36	9	RES 0.0 OHM 1/10W 0402 SMD	Panasonic - ECG	ERJ-2GE0R00X			
R13, R14, R21, R22, R23, R24, R25	7	RES 0.0 OHM 1/10W 0402 SMD	Panasonic - ECG	ERJ-2GE0R00X			
R4	1	RES Thick Film 680 OHM 1/10W 5% 0402	Panasonic - ECG	ERJ-2GEJ681X			
R19	1	RES 10K OHM 1/10W 5% 0402 SMD	Panasonic - ECG	ERJ-2GEJ103X			
R12, R15, R20	3	RES 10K OHM 1/10W 5% 0402 SMD	Panasonic - ECG	ERJ-2GEJ103X			
R27	1	RES 10K OHM 1/10W 5% 0402 SMD	Panasonic - ECG	ERJ-2GEJ103X			DO NOT INSTALL
R28	1	RES 100K OHM 1/10W 5% 0402 SMD	Panasonic - ECG	ERJ-2GEJ104X			DO NOT INSTALL
R34	1	RES 10.0K OHM 1/10W 1% 0402 SMD	Panasonic - ECG	ERJ-2RKF1002X			
RF1, RF2	2	SMT-20pin-30Au 50ni-Double Row-Alignment pin	Samtec	SFM-110-02-L-D-A			
SHLD1	1	BOARD SHIELD .65X.65" FRAME	Laird Technologies EMI	BMI-S-202-F			DO NOT INSTALL
TP1, TP2	2	TEST POINT .025" SQR POST HDR BLACK	Components Corporation	TP-105-01-00			
TP3, TP4, TP5	3	TP_VIA_030RND020	XX	XX			
U1	1	IC REG LDO 1.8V 0.15A SOT23-5	Texas Instruments	LP2985-18DBV			
U2, U4	2	IC BUS TRANSCVR 4BIT WITH 1.2-3.6V 16-UQFN	Texas Instruments	SN74AVC4T774RSV			
U3	1	IC BUS TRANSCVR 4BIT WITH 1.2-3.6V 16-UQFN	Texas Instruments	SN74AVC4T774RSV			
U5	1	Bluetooth BR/EDR/LE and ANT Single-Chip Solution	Texas Instruments	CC256xRVM			

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XSHLD1	1	BOARD SHIELD .650X.650" COVER	Laird Technologies EMI	BMI-S-202-C			DO NOT INSTALL
Y1	1	CRYSTAL 26MHz	NDK	NX2016SA (EXS00A- CS06025)			
R7, R10	2	805					DO NOT INSTALL
J1, J2	2	HDR_THVT_1x2_100_M	Samtec	HMTSW-102-07-G-S-230			

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